# Product End-of-Life Disassembly Instructions

**Product Category:** Notebooks and Tablet PCs

**Marketing Name / Model**

[List multiple models if applicable.]

| HP Envy 15 Notebook PC |

---

**Purpose:** The document is intended for use by end-of-life recyclers or treatment facilities. It provides the basic instructions for the disassembly of HP products to remove components and materials requiring selective treatment, as defined by EU directive 2002/96/EC, Waste Electrical and Electronic Equipment (WEEE).

## 1.0 Items Requiring Selective Treatment

1.1 Items listed below are classified as requiring selective treatment.

1.2 Enter the quantity of items contained within the product which require selective treatment in the right column, as applicable.

<table>
<thead>
<tr>
<th>Item Description</th>
<th>Notes</th>
<th>Quantity of items included in product</th>
</tr>
</thead>
<tbody>
<tr>
<td>Printed Circuit Boards (PCB) or Printed Circuit Assemblies (PCA)</td>
<td>With a surface greater than 10 sq cm</td>
<td>4</td>
</tr>
<tr>
<td>Batteries</td>
<td>All types including standard alkaline and lithium coin or button style batteries</td>
<td>2</td>
</tr>
<tr>
<td>Mercury-containing components</td>
<td>For example, mercury in lamps, display backlights, scanner lamps, switches, batteries</td>
<td></td>
</tr>
<tr>
<td>Liquid Crystal Displays (LCD) with a surface greater than 100 sq cm</td>
<td>Includes background illuminated displays with gas discharge lamps</td>
<td>1</td>
</tr>
<tr>
<td>Cathode Ray Tubes (CRT)</td>
<td></td>
<td></td>
</tr>
<tr>
<td>Capacitors / condensers (Containing PCB/PCT)</td>
<td></td>
<td></td>
</tr>
<tr>
<td>Electrolytic Capacitors / Condensers measuring greater than 2.5 cm in diameter or height</td>
<td></td>
<td></td>
</tr>
<tr>
<td>External electrical cables and cords</td>
<td></td>
<td>0</td>
</tr>
<tr>
<td>Gas Discharge Lamps</td>
<td></td>
<td></td>
</tr>
<tr>
<td>Plastics containing Brominated Flame Retardants weighing &gt; 25 grams (not including PCBs or PCAs already listed as a separate item above)</td>
<td></td>
<td></td>
</tr>
<tr>
<td>Components and parts containing toner and ink, including liquids, semi-liquids (gel/paste) and toner</td>
<td>Include the cartridges, print heads, tubes, vent chambers, and service stations.</td>
<td></td>
</tr>
<tr>
<td>Components and waste containing asbestos</td>
<td></td>
<td></td>
</tr>
</tbody>
</table>
Components, parts and materials containing refractory ceramic fibers

Components, parts and materials containing radioactive substances

### 2.0 Tools Required

List the type and size of the tools that would typically be used to disassemble the product to a point where components and materials requiring selective treatment can be removed.

<table>
<thead>
<tr>
<th>Tool Description</th>
<th>Tool Size (if applicable)</th>
</tr>
</thead>
<tbody>
<tr>
<td>Motor Screw Driver &quot;+&quot;</td>
<td>Cross head of screwdriver</td>
</tr>
<tr>
<td>Description #2</td>
<td></td>
</tr>
<tr>
<td>Description #3</td>
<td></td>
</tr>
<tr>
<td>Description #4</td>
<td></td>
</tr>
<tr>
<td>Description #5</td>
<td></td>
</tr>
</tbody>
</table>

### 3.0 Product Disassembly Process

3.1 List the basic steps that should typically be followed to remove components and materials requiring selective treatment:

1. Reverse machine, slide battery lock, and then take out battery.
2. Loosen HDD cover screw *1, take out service door. 
3. Pull out HDD cable and pull out HDD module then take out HDD.
4. Pull out WLAN cable *2
5. Loosen screw *1, take out WLAN card. 
6. Take out Lower rubber foot *2.
7. Loosen BTCB screw *20 in order.
8. Disassemble BTM case. 
10. Release Antenna Cable. 
11. Pull out Webcam and LVDS Cable. 
12. Loosen screw *4, take out LCD module. 
13. Take out screw mylar *2, Loosen screw *2
15. Loosen screw *2, take out hinge cap L/R. 
16. Release Webcam Cable, then take out. 
17. Loosen screw *4, take out LCD module. 
18. Pull out LVDS cable, then take out LVDS cable. 
19. Release Antenna cable, then take out Antenna cable. 
20. Loosen screw *8, then take hinge cover L/R and Hinge bracket L/R. 
21. Loosen screw *3, then take out bracket L/R. 
22. Loosen screw *2, pull out Fan cable then take out Thermal Fan module. 
23. Loosen screw *4(UMA) *8(DIS), then take out Thermal fin module. 
24. Pull out DC in cable, then take DC in cable. 
25. Pull out USB board FFC(2 side), then take out USB board FFC. 
26. Pull out USB board cable(2 side), then take out USB board cable. 
27. Loosen screw *2, then take out USB board. 
28. Loosen screw *2, and pull out sbu woofe cable, then take out sub woofer module. 
29. Loosen screw *1, then take out finger print bracket. 
30. Pull out finger print FFC(2 side), then take finger print FFC and finger print module. 
31. Loosen screw *4, pull out speaker cable, then take out speaker module L/R. 
32. Pull out speaker front cable, Touch pad FFC, Keyboard FFC, Power board FFC.
33. Disassemble DDR
34. Loosen screw *9, then take out Main Board.
35. Loosen screw *3, then take out speaker front module L/R.
36. Loosen screw *2, then take out pick button bracket.
37. Pull out touch pad FFC, then take out touch pad FFC.
38. Loosen screw *2, then take out touch pad module.
39. Loosen screw *1, then take out power board module.
40. Loosen screw *5, then slide out keyboard support bracket.
41. Loosen screw * then slide out keyboard.
42.

3.2 Optional Graphic. If the disassembly process is complex, insert a graphic illustration below to identify the items contained in the product that require selective treatment (with descriptions and arrows identifying locations).

3.21 Total part disassembly
3.22 Remove battery module
3.23 Remove service door
3.24 LCD module set disassembly
3.25 Top case disassembly
3.26 Thermal module and mother board disassembly
3.27 Bottom case disassembly